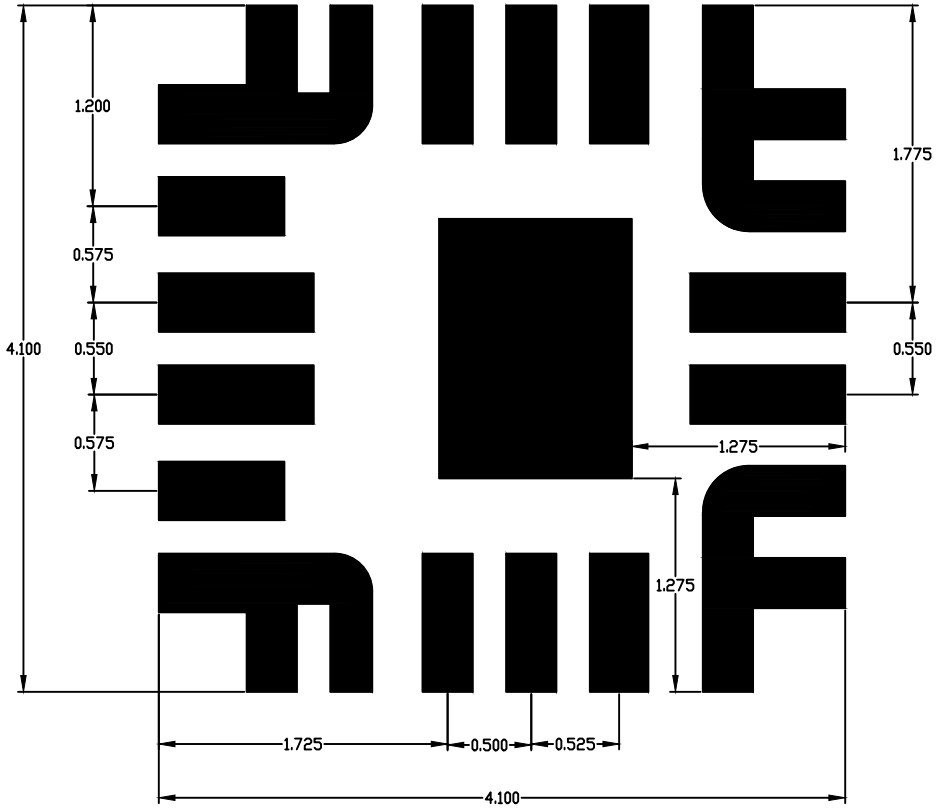
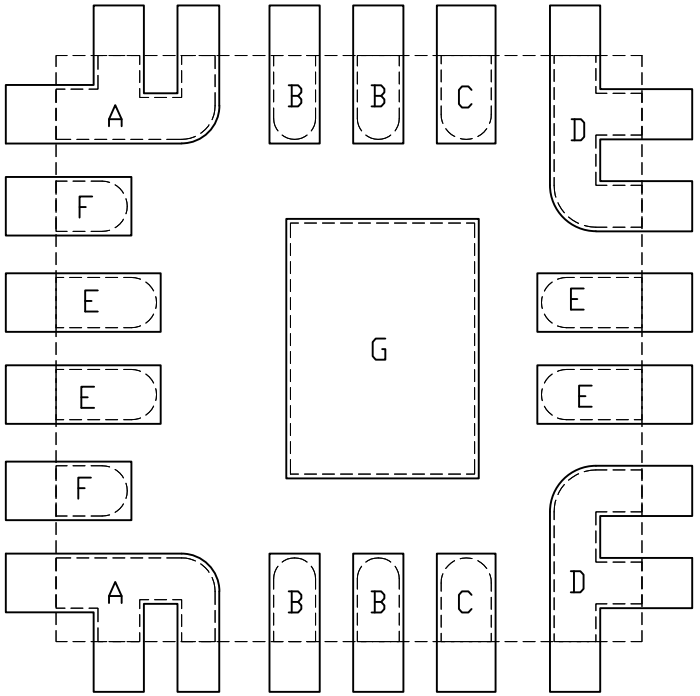
DOCUMENT TYPE:	**PLP**
DOCUMENT ID #:	**90-100232**
REVISION:	**B-000**
DOCUMENT TITLE:	**PACKAGE LAND PATTERN, [F163B3FY+1] FC2QF**
EFFECTIVE DATE:	**11/16/2022**
EXPIRATION DATE:	
CHANGE NUMBER:	**1175976**
ORIGINATOR:	**Bernard Go**

REASON FOR CHANGE:
LF design change per BU request.

RECOMMENDED LAND PATTERN



PACKAGE OVERLAY



NOTES:

1. REFERENCE PKG. OUTLINE: 21-100664
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. TOLERANCE: +/- 0.02 MM.
4. ALL DIMENSIONS APPLY TO LEADED, PbFREE PACKAGES.
5. ALL DIMENSIONS IN MM.

-DRAWING NOT TO SCALE-

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ANALOG DEVICES

TITLE:
PACKAGE LAND PATTERN,
[F163B3FY+1] FC2QFN

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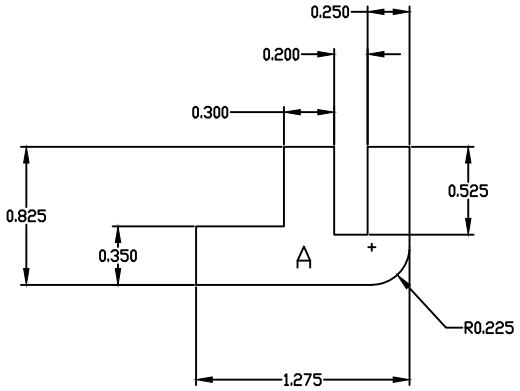
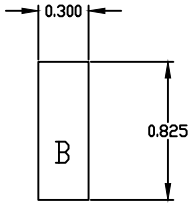
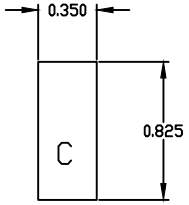
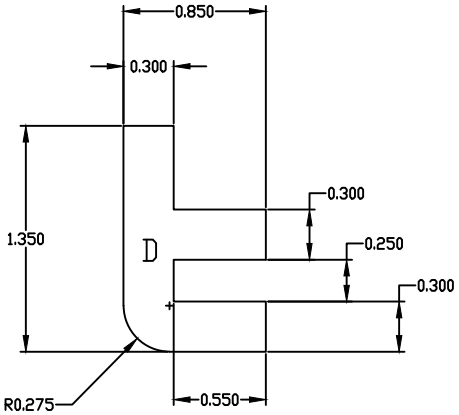
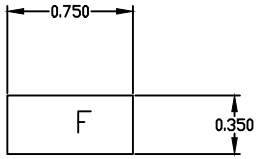
PAD DETAILS

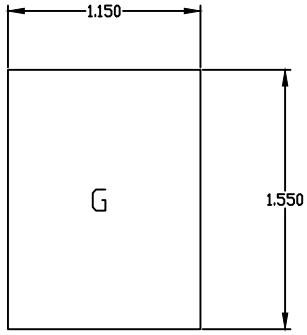


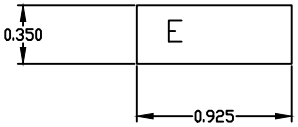












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APPROVAL: ZHEN LI	DOCUMENT CONTROL NO.: 90-100232	REV.: B	2/2

pREVISION HISTORY

REV	CHANGES MADE	DATE	INIT.
A	CN 1166024 Initial Release	06/22/22	BG
B	CN 1175976. LF design change per BU request.	11/16/2022	BG